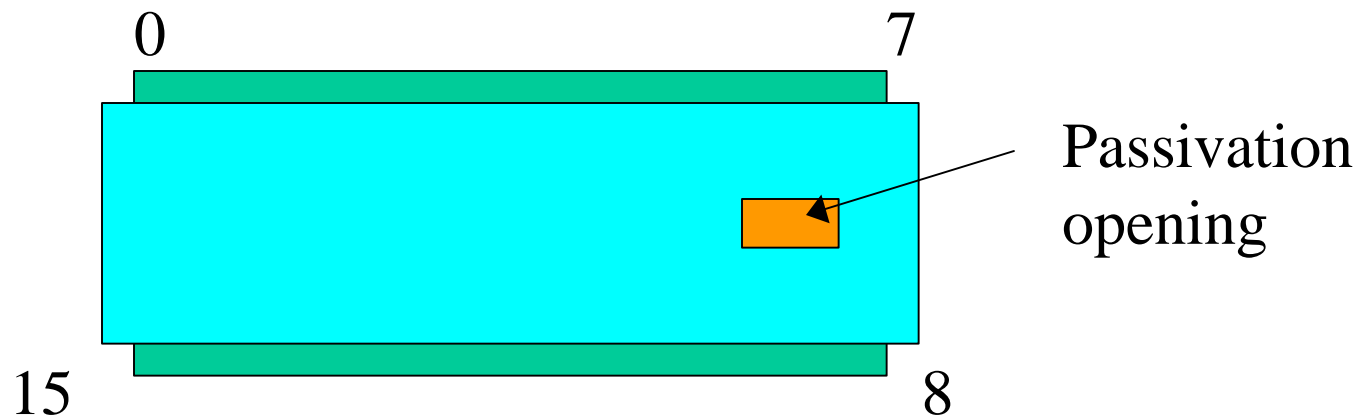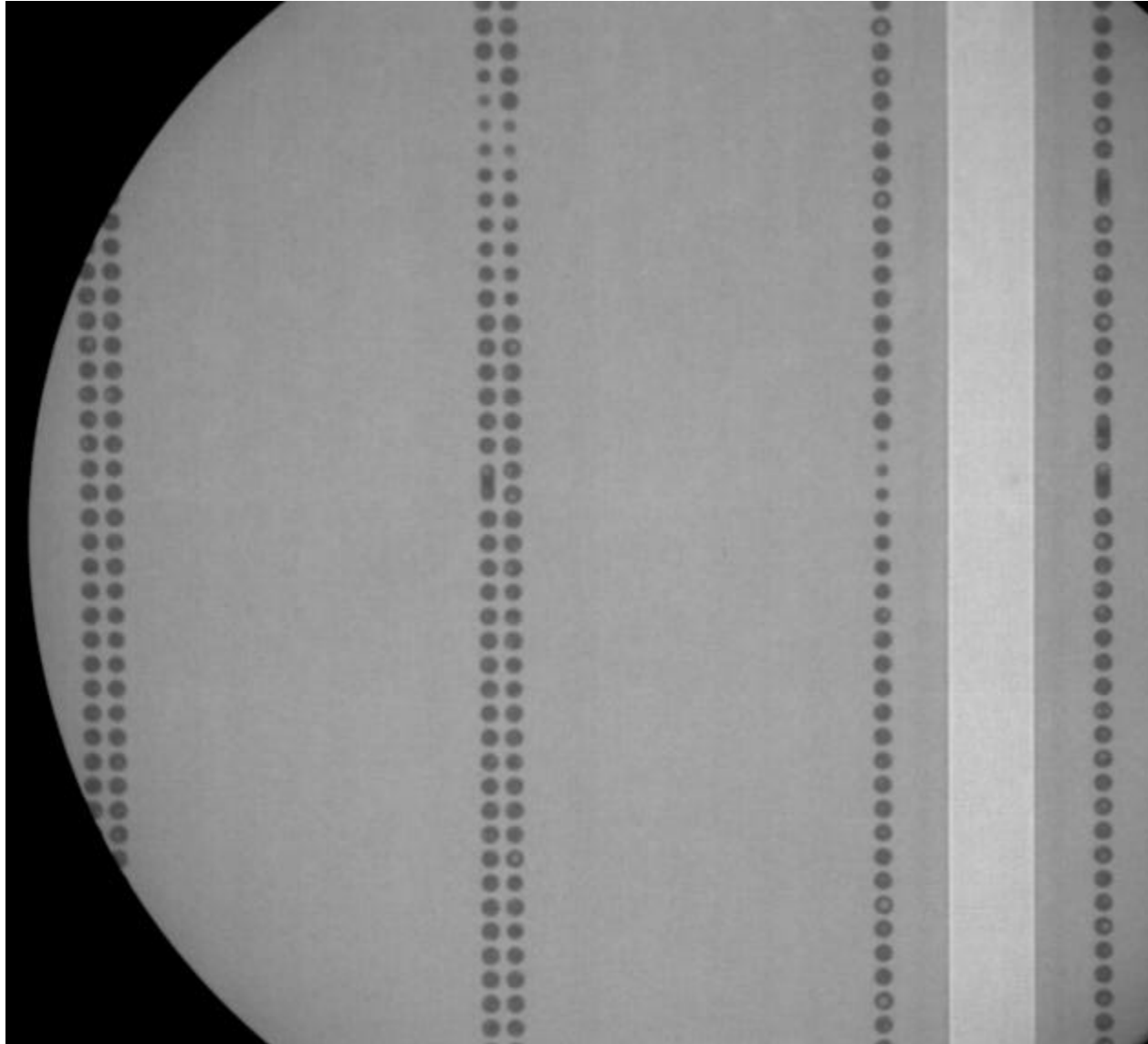# X-Ray of IZM Parts

M. Gilchriese

April 1999

Method

- X-Ray of modules and single chip assemblies at X-Tek

- All done in gelpaks

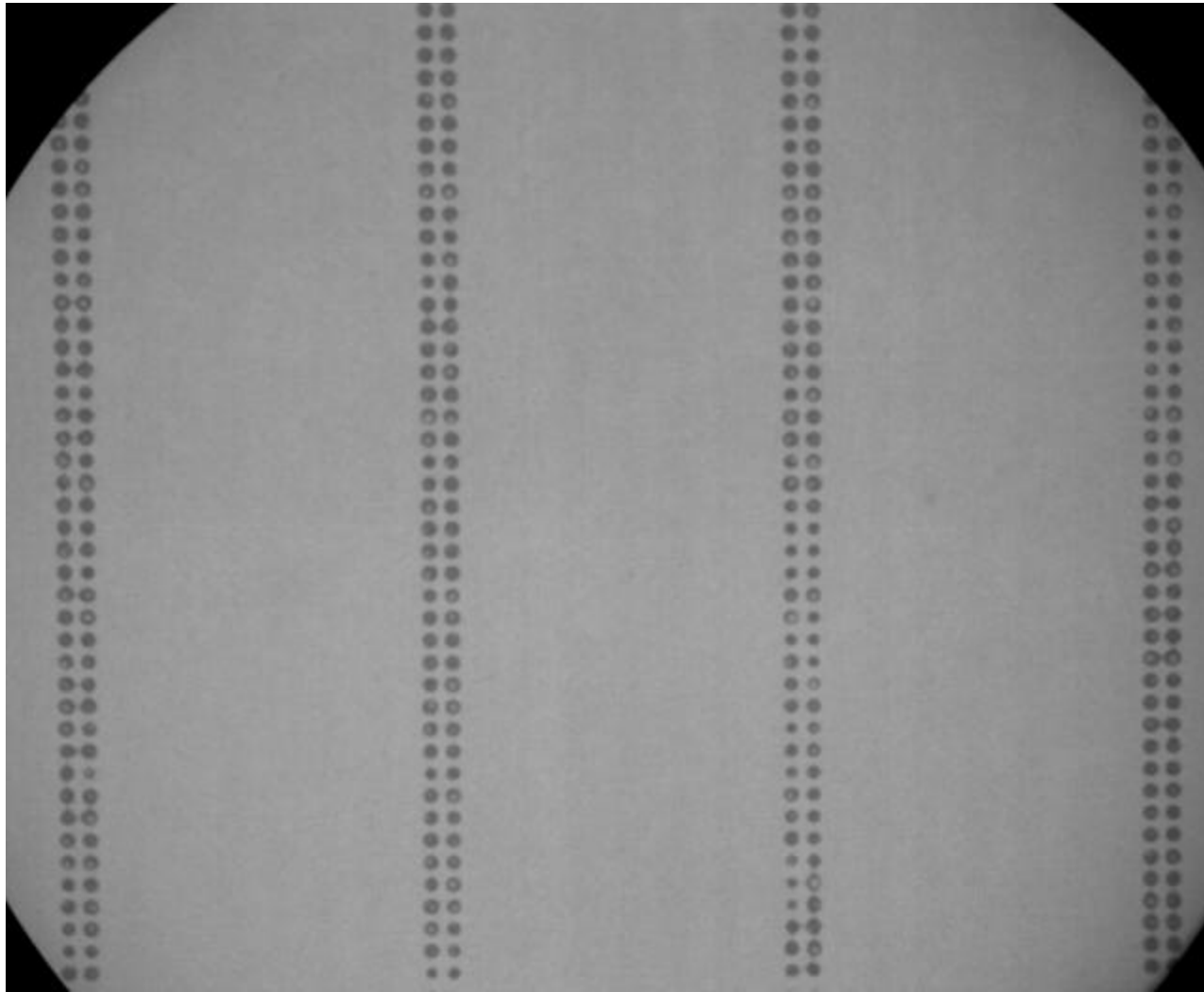- Chip numbering convention used is different than IZM and is shown in drawing
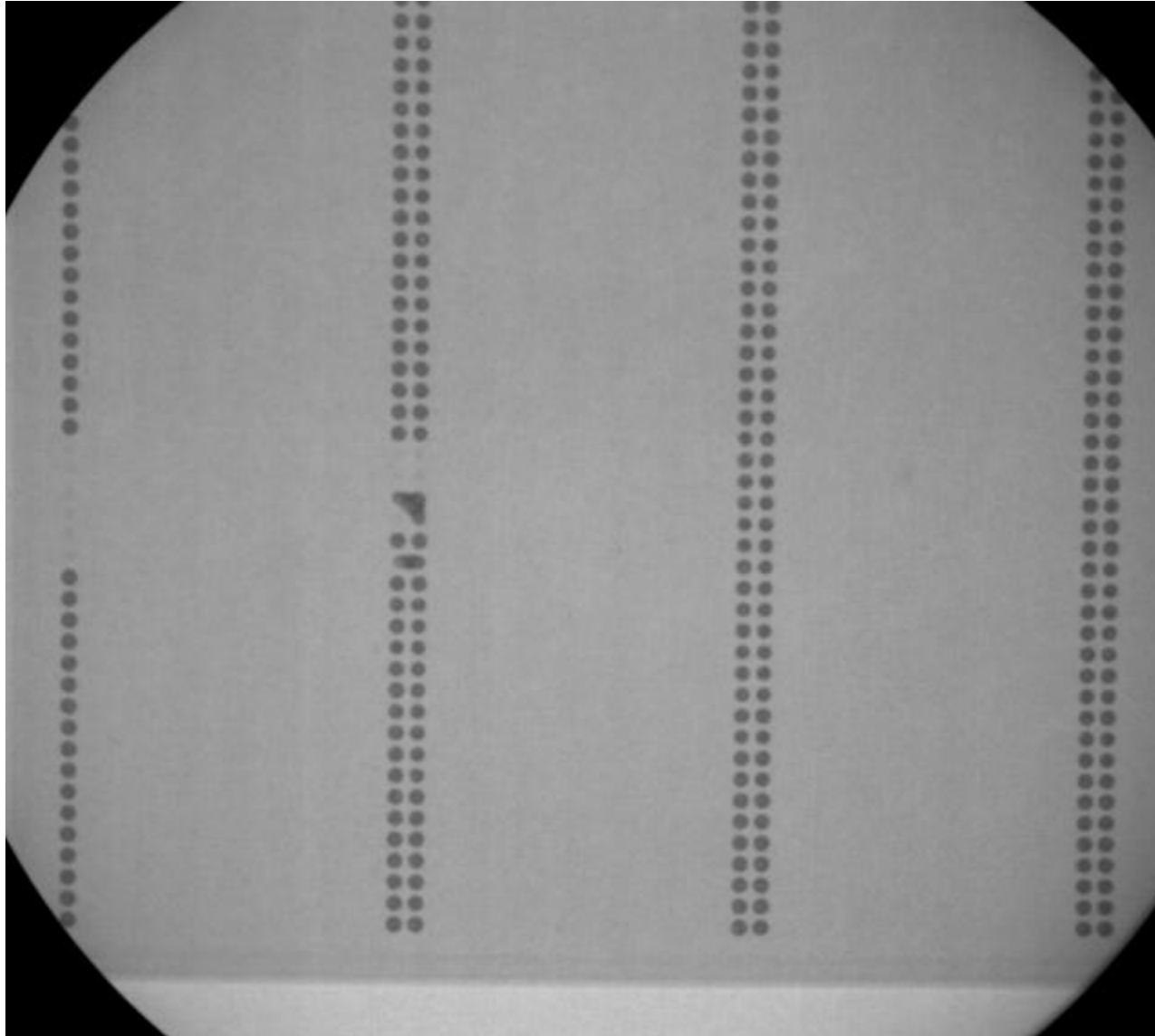
3135-11 Chip 1

- This picture shows typical region when merged bumps are present in single column.

- Also shows small region of smaller than normal bumps

3135-11 Chip 10

- Large region of smaller bumps mixed with normal size bumps

3134-21 Chip 4

- Region of missing and few merged bumps